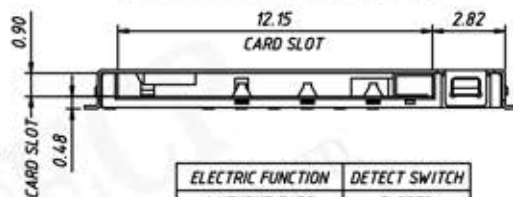
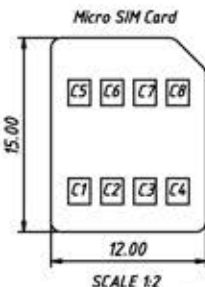


RECOMMENDED PCB LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)



ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	CLOSED
CARD INSERTED	OPEN



Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

Material:

Housing:Hi-temp Thermoplastic,UL 94 V-0,Black
Data Contact:Copper Alloy,Gold plated
CD Switch:Copper Alloy,Gold plated
Shell:Stainless Steel,Gold plated
Coil Spring:SWP
Heart CAM:Hi-temp Thermoplastic,UL 94 V-0,Black
CAM PIN:Stainless Steel

Technical Characteristics

1.General Characteristics

Dimensions:15.75L×17.17W×1.50H mm

Weight:Approx0.4±0.1g

Durability:1500 cycles min.

2.Electrical Characteristics

Contact resistance:150mΩ typical,500mΩ max

Insulation resistance:>1000Ω/500V DC

3.Solderability

Vapor phase:215℃,30sec.Max

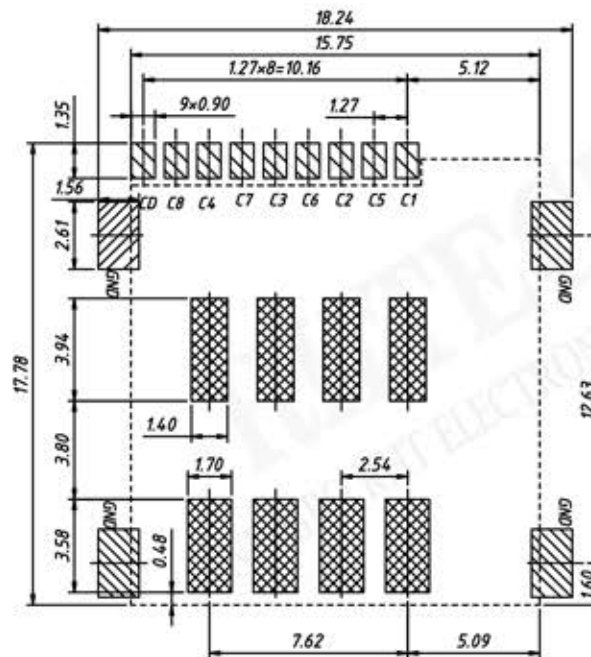
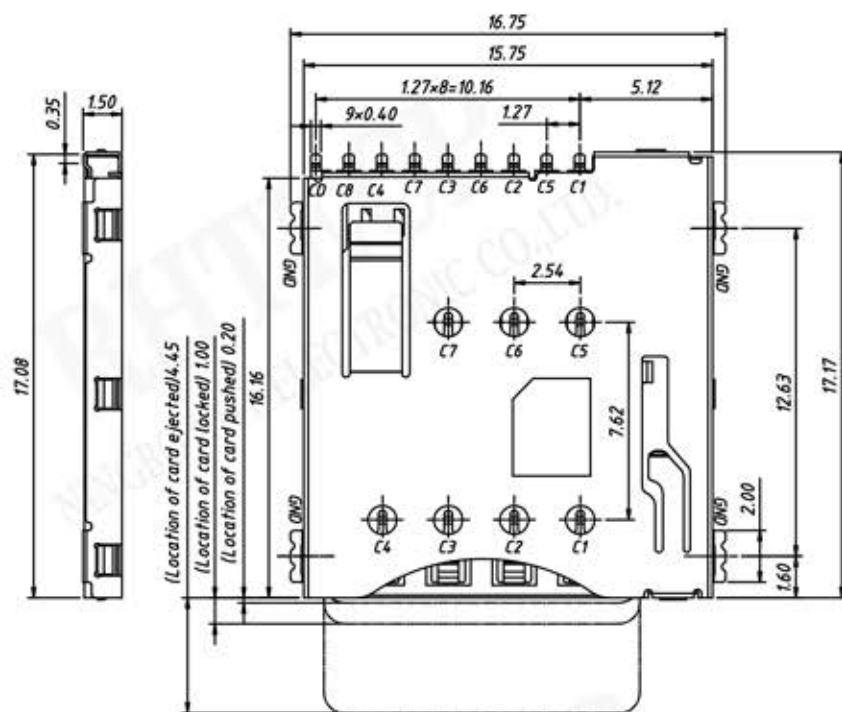
IR reflow:250℃,5sec.Max

Manual soldering:370℃,3sec.Max

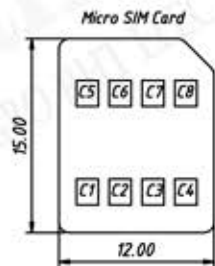
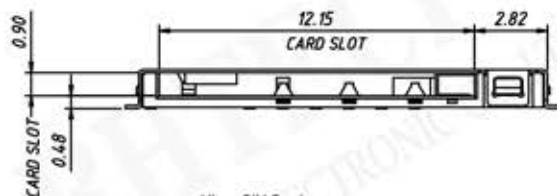
4.Environmental Characteristics

Operating temperature:-40℃- +85℃

Operating humidity:10%- +95%RH



PAD AREA
 KEEP OUT AREA
RECOMMENDED PCB LAYOUT
 COMPONENT SIDE (TOLERANCE ±0.05)



ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	CLOSED
CARD INSERTED	OPEN



Electrical
 Current Rating: 0.5A
 Voltage Rating: 5.0 vrms
 Contact resistance: 100mΩ Max.
 Insulation resistance: 1000M Min.
 Withstanding Voltage: 250V ACrms
 For 1 Minute.
 Operating Temp Range: -40°C - +85°C
 Mating Cycles: 1500 Insertions

Material:
 Insulator: Hi-Temperature plastic, UL 94V-0, Black
 Terminal: Copper Alloy, Gold Flash Plating On All Terminal, And 50u" min nickel underplated on allover.
 Shell: Stainless Steel, 50u" Nickel underplated on allover, gold flash on solder pad.

Micro SIM Card	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved